

10/540528

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**Application Data Sheet**

**Application Information**

Application Type::	Regular
Subject Matter::	National Phase
Suggested Group Art Unit::	N/A
CD-ROM or CD-R?::	None
Sequence submission?::	None
Computer Readable Form (CRF)?::	No
Title::	CURABLE RESIN COMPOSITION AND CURED PRODUCT
Attorney Docket Number::	4924-0112PUS1
Request for Early Publication?::	No
Request for Non-Publication?::	No
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

**Applicant Information**

Applicant Authority Type::	Inventor
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Status::	Full Capacity
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**Correspondence Information**

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Correspondence Customer Number:: 02292

**Representative Information**

Representative Customer Number:: 02292

**Domestic Priority Information**

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application is a	National Stage of	PCT/JP2003/016568	12/24/03

**Foreign Priority Information**

Country::	Application number::	Filing Date::	Priority Claimed::
Japan	2002-381563	12/27/02	Yes

**Assignee Information**

Assignee name:: Daicel Chemical Industries, Ltd.  
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